

November 2, 2020

(Progress of a Disclosed Item)

**Notice of the Completion of Payment for New Shares through Third-Party Allotment by the
Subsidiary that Manufactures Semiconductor Wafer**

With regard to the issuance of new shares through third-party allotment of Hangzhou Semiconductor Wafer Co., Ltd., a consolidated subsidiary of the Company, which was announced in “Notice of the Issuance of New Shares through Third-Party Allotment by the Subsidiary that Manufactures Semiconductor Wafer” dated October 16, 2020, the payment of the amount to be raised: 1,599,998 thousand yuan (approx. 25.12 billion yen) has been completed by the settlement date. We plan to allocate said funds to mainly invest in the semiconductor wafer manufacturing facilities. We will announce details on said capital investment when they are finalized.